



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-02-10
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
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Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
SCT055TO65G3	V39X*BRF5BVF	A	Z8GA	2025-02-10
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	697.00	mg	Each	ECOPACK® 2
Identity	Authority			
Comment	0			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
CHP	9.9x10.38	8	no lead
Comment			
Comment	A09X TO-LL		

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 3rd January 2025			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.050	alloy	72
Lead	3.319	solder	4762

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				Response
QUERY				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				true
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
X	O	O	O	O
Soft solder				
Homogeneous Material(s) containing Lead				

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead (Pb)	1000 ppm	3.32	Soft solder	4762
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
Lead dinitrate	1000 ppm	3.319	Soft solder	954833



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene, Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	V39X*BRF5BVF			697.0000		7000000.0	999998.0
note : Substance present with less 0.001mg will not be declared in this document													
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	3.390	mg	supplier	die	Silicon(Si)	7440-21-3		0.014	mg	4130	20	
	M-011 Other inorganic materials			California 65	die	Silicium carbide	409-21-2		3.177	mg	937168	4558	
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.058	mg	17109	83	
				supplier	metallisation	Copper(Cu)	7440-50-8		0.008	mg	2360	11	
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.050	mg	14749	72	
				supplier	metallisation	Silver(Ag)	7440-22-4		0.051	mg	15044	73	
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.006	mg	1770	9	
				supplier	metallisation	Vanadium(V)	7440-62-2		0.002	mg	590	3	
				supplier	Passivation	Silicon nitride(S	12033-89-5		0.009	mg	2655	13	
				supplier	passivation	Silicon oxide	7631-86-9		0.015	mg	4425	22	
Leadframe	M-004 Copper and its alloys	312.569	mg	supplier	alloy	Copper(Cu)	7440-50-8		312.162	mg	998698	447865	
				supplier	alloy	Iron phosphide	26508-33-8		0.263	mg	841	377	
				supplier	alloy	Iron(Fe)	7439-89-6		0.144	mg	461	207	
Soft solder	Solder	3.476	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	3.319	mg	954833	4762	
				supplier	solder	Tin(Sn)	7440-31-5		0.070	mg	20138	100	
				supplier	solder	Silver(Ag)	7440-22-4		0.087	mg	25029	125	
Bonding wires	M-003 Aluminum and its alloys	1.970	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.970	mg	1000000	2826	
Bonding wires 2	M-003 Aluminum and its alloys	0.239	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.239	mg	1000000	343	
Encapsulation	M-011 Other inorganic materials	373.080	mg	supplier	mold compound	Silica vitreous	60676-86-0		302.850	mg	811756	434505	
				supplier	mold compound	Silicon oxide	7631-86-9		27.796	mg	74504	39879	
				supplier	mold compound	Epoxy type resi	proprietary		27.796	mg	74504	39879	
				supplier	mold compound	Phenol type res	proprietary		11.118	mg	29801	15951	
				supplier	mold compound	Carbon black	1333-86-4		2.038	mg	5463	2924	
				supplier	mold compound	Bismuth compo	7440-69-9		1.482	mg	3972	2126	
Connections coating	Solder	2.276	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		2.276	mg	1000000	3265	